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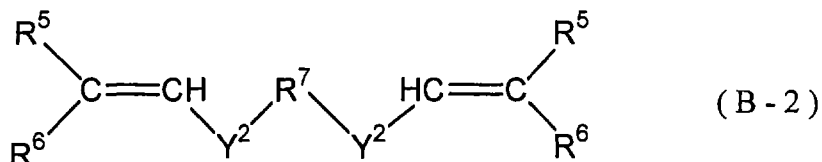
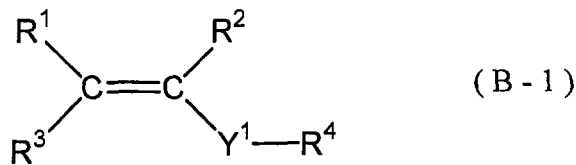
ABSTRACT

A photosemiconductor encapsulating resin composition, excellent in light transmittance, ultraviolet resistance and heat resistance, comprising the following component (A) and component (B):

(A): a (meth)acrylic polymer containing an epoxy group, and

(B): at least one hardener selected from the group consisting of the following components (b₁) to (b₄):

- (b₁) a polyvalent carboxylic acid,
 (b₂) a polyvalent carboxylic anhydride,
 (b₃) a reaction product of a polyvalent carboxylic acid with a compound of the following general formula (B-1), and
 (b₄) a reaction product of a polyvalent carboxylic anhydride with a compound of the following general formula (B-2)



wherein R¹ to R⁶ represent each independently a hydrogen atom or an alkyl group having 1 to 8 carbon atoms, R³ and R⁴ may be bonded to form an alkylene group having 1 to 8 carbon atoms; R⁷ represents an alkylene group; a methylene



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group contained the alkylene group and the alkyl group represented by R^1 to R^7 may be substituted by an ether group and/or carbonyl group; Y^1 and Y^2 represent each independently an oxygen atom, or sulfur atom,

5 is provided.